



TE Internal #: 1-1473005-1
 SO DIMM Sockets, Double Data Rate (DDR), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, 200 Position, .024 in [.6 mm] Centerline

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR2 SO DIMM Sockets



DRAM Type: **Double Data Rate (DDR)**
 Stack Height: **5.2 mm [.205 in]**
 Module Orientation: **Right Angle**
 Connector System: **Cable-to-Board**
 Number of Positions: **200**

[All DDR2 SO DIMM Sockets \(30\)](#)

Features

Product Type Features

| | |
|-----------------------------------|------------------------|
| DRAM Type | Double Data Rate (DDR) |
| Connector System | Cable-to-Board |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| | |
|---------------------|-------------|
| Number of Bays | 2 |
| Number of Keys | 1 |
| Number of Rows | 2 |
| Module Orientation | Right Angle |
| Number of Positions | 200 |

Electrical Characteristics

| | |
|--------------|-------|
| DRAM Voltage | 2.5 V |
|--------------|-------|

Signal Characteristics

| | |
|---------------|-------|
| SGRAM Voltage | 2.5 V |
|---------------|-------|



Body Features

| | |
|------------------------|-----------------|
| Ejector Location | Both Ends |
| Latch Material | Stainless Steel |
| Latch Plating Material | Tin |
| Module Key Type | SGRAM |
| Ejector Type | Locking |
| Connector Profile | Standard |

Contact Features

| | |
|------------------------------------------------|--------------------------|
| Memory Socket Type | Memory Card |
| PCB Contact Termination Area Plating Material | Gold Flash |
| Contact Base Material | Copper Alloy |
| Contact Mating Area Plating Material | Gold Flash |
| Contact Mating Area Plating Material Thickness | .76 μ m[30 μ in] |
| Contact Current Rating (Max) | .5 A |

Termination Features

| | |
|-----------------|--------|
| Insertion Style | Cam-In |
|-----------------|--------|

Mechanical Attachment

| | |
|--------------------------|-----------------|
| Mating Alignment Type | Standard Keying |
| PCB Mounting Style | Surface Mount |
| PCB Mount Retention | With |
| PCB Mount Retention Type | Solder Peg |
| Connector Mounting Type | Board Mount |

Housing Features

| | |
|--------------------|--------------------------------|
| Housing Material | High Temperature Thermoplastic |
| Housing Color | Black |
| Centerline (Pitch) | .6 mm[.024 in] |

Dimensions

| | |
|--------------------|-----------------|
| Stack Height | 5.2 mm[.205 in] |
| Row-to-Row Spacing | 6.2 mm[.244 in] |

Usage Conditions

| | |
|-----------------------------|---------------------------|
| Operating Temperature Range | -55 – 85 °C[-67 – 185 °F] |
|-----------------------------|---------------------------|

Operation/Application



Circuit Application

Power

Industry Standards

UL Flammability Rating

UL 94V-0

Packaging Features

Packaging Quantity

20

Packaging Method

Semi-Hard Tray Assembly

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU

Compliant

EU ELV Directive 2000/53/EC

Compliant

China RoHS 2 Directive MIIT Order No 32, 2016

No Restricted Materials Above Threshold

EU REACH Regulation (EC) No. 1907/2006

Current ECHA Candidate List: JUNE 2023 (235)
 Candidate List Declared Against: JUNE 2023 (235)
 Does not contain REACH SVHC

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Reflow solder capable to 245°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Customers Also Bought



TE Part #4-1879233-4
SMW5 6R2 5%



TE Part #5-2176231-3
3522 1K5 1% 3W



TE Part #9-1879208-2
CPF 0402 62K 0.1% 25PPM 1K RL



TE Part #4-1625867-2
RP 1J 0.166W 16R5 0.1% 25PPM 1K RL



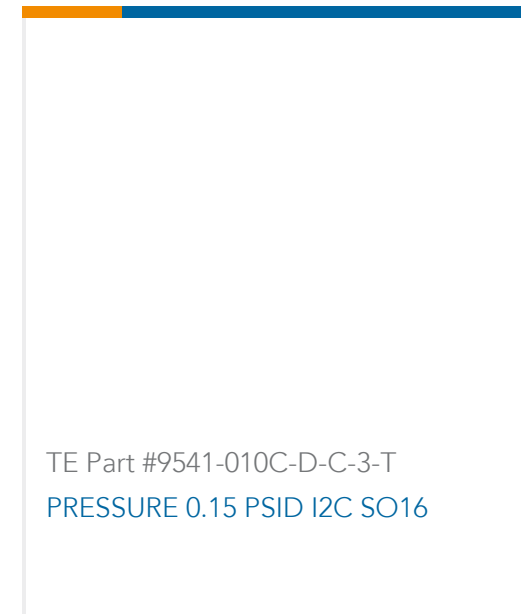
TE Part #2842126-5
10P,2MM,BRK HDR,DRVT,2.8,0.1AU,TB



TE Part #1-2176325-4
CRGP 0402 120R 1%



TE Part #6-2176243-9
CRGS0603 5% 470K



TE Part #9541-010C-D-C-3-T
PRESSURE 0.15 PSID I2C SO16

Documents

Product Drawings

SEMI HARD TRAY DDR SOCKET 200P

English

CAD Files

Customer View Model

[ENG_CVM_CVM_1-1473005-1_J1.2d_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_1-1473005-1_J1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1-1473005-1_J1.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

Product Specification

English

Product Environmental Compliance

[MD_1-1473005-1_013120182147_dmtec](#)

English

[MD_1-1473005-1_013120182147_dmtec](#)

English

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